

CMSLG65R015

650V, 18mΩ typ., 135A N-Channel Silicon Carbide Power MOSFET

General Description

This silicon carbide Power MOSFET device has been developed using Cmos's advanced SiC MOSFET technology. The device features a very low $R_{DS(on)}$ over the entire temperature range combined with low capacitances and very high switching operations, which improve application performance in frequency, energy efficiency, system size and weight reduction.

Features

- Wide Bandgap SiC MOSFET Technology
- High switching speed with a low gate charge
- Fast intrinsic diode with low reverse recovery
- RoHS Compliant

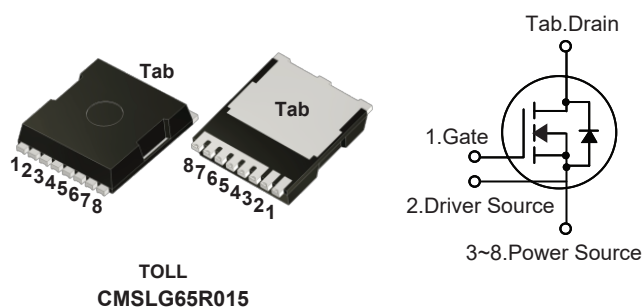
Product Summary

BVDSS	$R_{DS(on)}$ typ.	ID
650V	18mΩ	135A

Applications

- inverter
- EV charging infrastructure
- uninterruptable power supplies

TOLL Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	650	V
V_{GS}	Absolute maximum values	-10/+22	V
V_{GSop}	Recommended operational values	-5/+18	V
$I_D@T_C=25^{\circ}C$	Continuous Drain Current	135	A
$I_D@T_C=100^{\circ}C$	Continuous Drain Current	96	A
I_{DM}	Pulsed Drain Current	375	A
EAS	Single Pulse Avalanche Energy (Note 1)	4335	mJ
$P_D@T_C=25^{\circ}C$	Total Power Dissipation	500	W
T_{STG}	Storage Temperature Range	-55 to 175	$^{\circ}C$
T_J	Operating Junction Temperature Range	-55 to 175	$^{\circ}C$

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient	---	40	$^{\circ}C/W$
$R_{\theta JC}$	Thermal Resistance Junction-case	---	0.30	$^{\circ}C/W$

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Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V$, $I_D=2mA$	650	---	---	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=18V$, $I_D=30A$	---	18	22	mΩ
		$V_{GS}=18V$, $I_D=30A$, $T_J=175^{\circ}\text{C}$	---	22	---	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=20.3mA$ (tested after $V_{GS}=22V$, 1ms pulse)	1.8	2.4	4.5	V
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=650V$, $V_{GS}=0V$	---	1	100	μA
		$V_{DS}=650V$, $V_{GS}=0V$, $T_J=175^{\circ}\text{C}$	---	10	---	
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=-10V$ to $22V$, $V_{DS}=0V$	---	---	±100	nA
g_{fs}	Forward Transconductance	$V_{DS}=20V$, $I_D=20A$	---	7.5	---	S
R_g	Gate Resistance	$V_{DS}=0V$, $V_{GS}=0V$, $f=1MHz$	---	2.2	---	Ω
$Q_{g(tot)}$	Total Gate Charge	$V_{DS}=400V$, $I_D=60A$ $V_{GS}=-5V$ to $18V$	---	146	---	nC
Q_{gs}	Gate-Source Charge		---	45	---	
Q_{gd}	Gate-Drain Charge		---	36	---	
E_{oss}	Stored Energy in Output Capacitance	$V_{GS}=0V$, $V_{DS}=0V$ to $400V$	---	36.5	---	μJ
$C_{o(er)}$	Energy Related Output Capacitance		---	456	---	pF
$C_{o(tr)}$	Time Related Output Capacitance		---	648	---	
E_{on}	Turn-on Switching Energy	$V_{DS}=400V$ $I_D=60A$ $V_{GS}=-5V$ / $18V$ $R_G=5.6\Omega$ FWD = 650V 20A SiC Diode Inductive load	---	146	---	μJ
E_{off}	Turn-off Switching Energy		---	279	---	
E_{tot}	Total Switching Energy		---	425	---	
$T_{d(on)}$	Turn-On Delay Time		---	29	---	ns
T_r	Rise Time		---	26	---	
$T_{d(off)}$	Turn-Off Delay Time		---	60	---	
T_f	Fall Time		---	10.5	---	
C_{iss}	Input Capacitance	$V_{DS}=100V$, $V_{GS}=0V$, $f=250kHz$	---	3500	---	pF
C_{oss}	Output Capacitance		---	680	---	
C_{rss}	Reverse Transfer Capacitance		---	35	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	$V_G=V_D=0V$, Force Current	---	---	135	A
I_{SM}	Pulsed Source Current		---	---	375	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0V$, $I_{SD}=30A$, $T_J=25^{\circ}\text{C}$	---	3.7	---	V
t_{rr}	Reverse Recovery Time	$di/dt=1000A/\mu s$, $V_{GS}=0V$	---	30	---	ns
Q_{rr}	Reverse Recovery Charge	$V_{DD}=400V$, $I_F=60A$, $T_J=25^{\circ}\text{C}$	---	303	---	nC

Note :

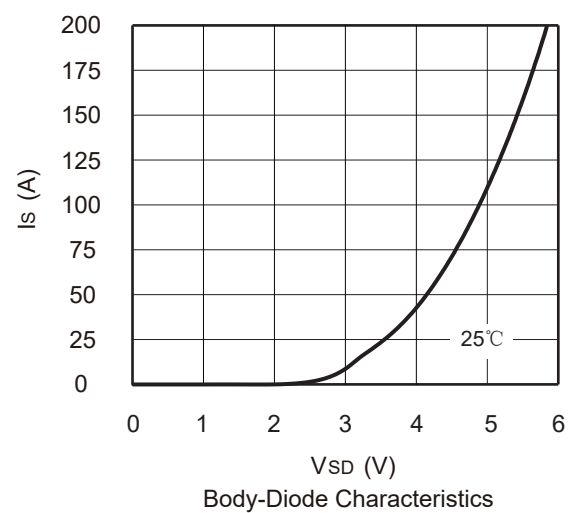
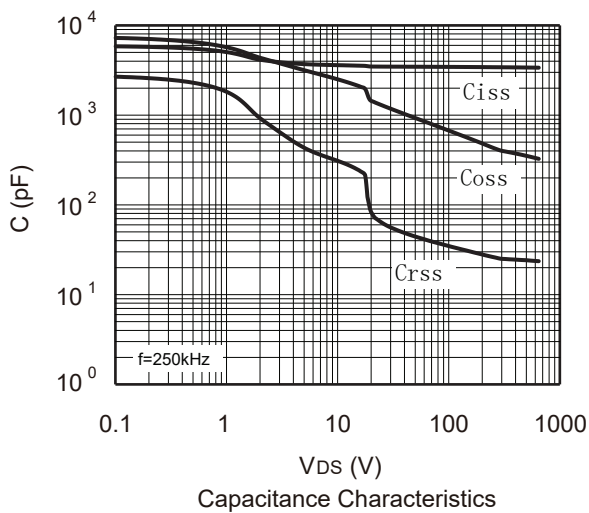
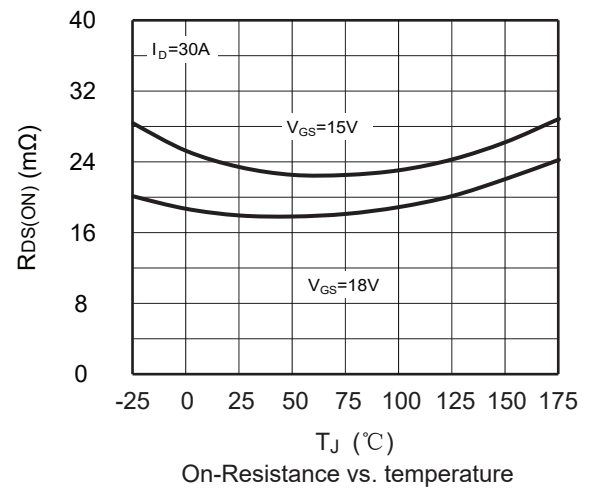
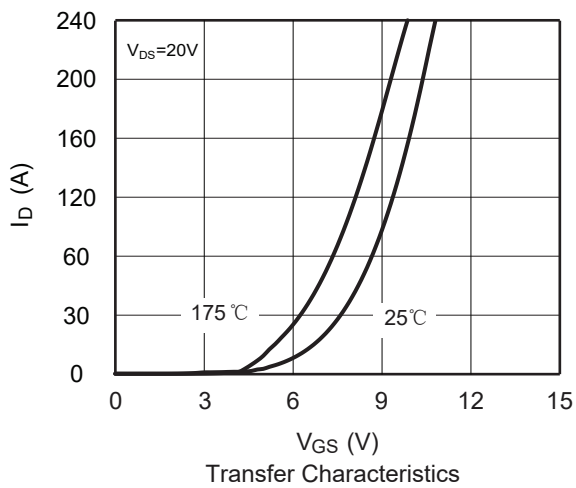
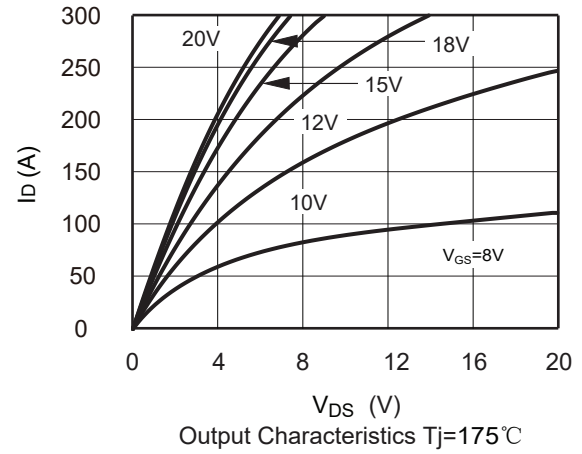
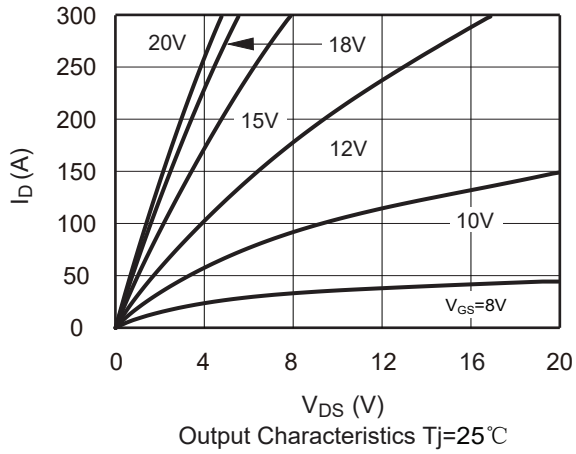
1. The EAS data shows Max. rating . The test condition is $V_{DD}=100V$, $V_{GS}=10V$, $L=30mH$, $I_{AS}=17A$.

This product has been designed and qualified for the consumer market.

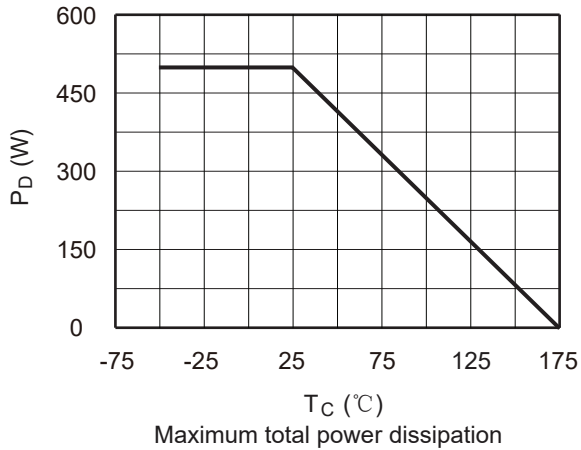
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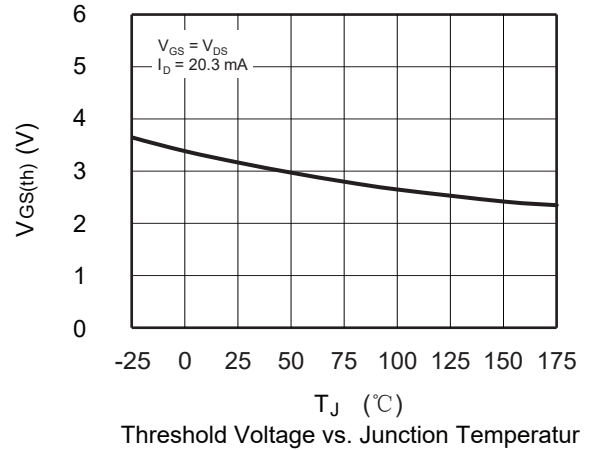
Typical Characteristics



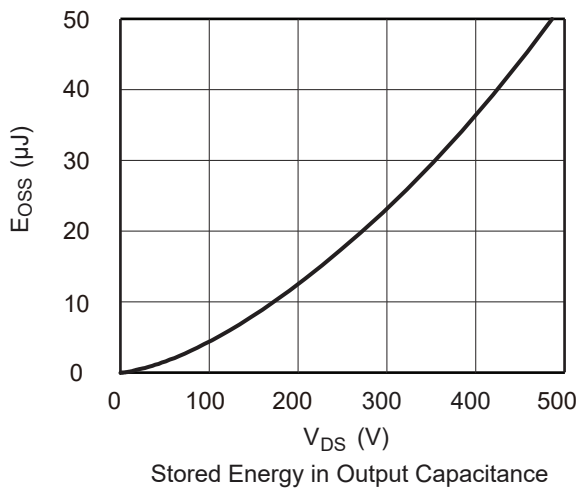
Typical Characteristics



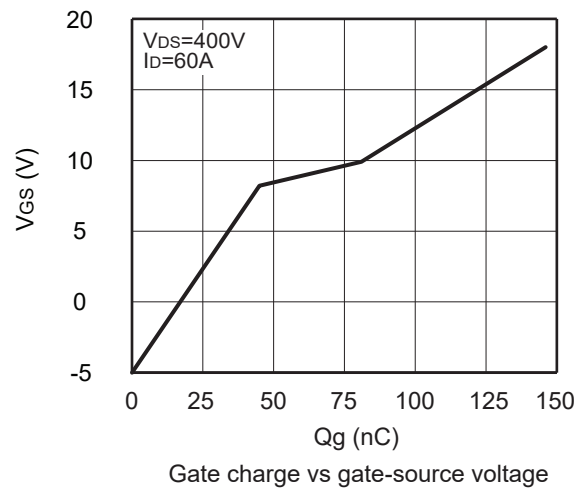
Maximum total power dissipation



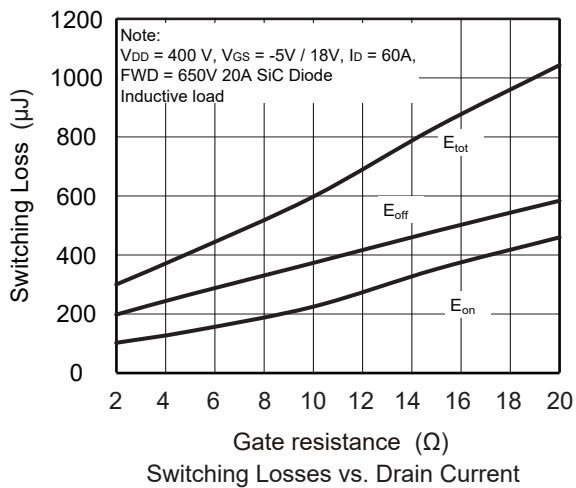
Threshold Voltage vs. Junction Temperature



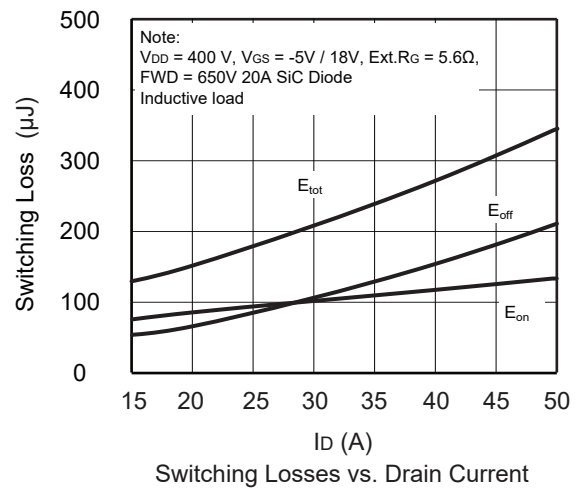
Stored Energy in Output Capacitance



Gate charge vs. gate-source voltage

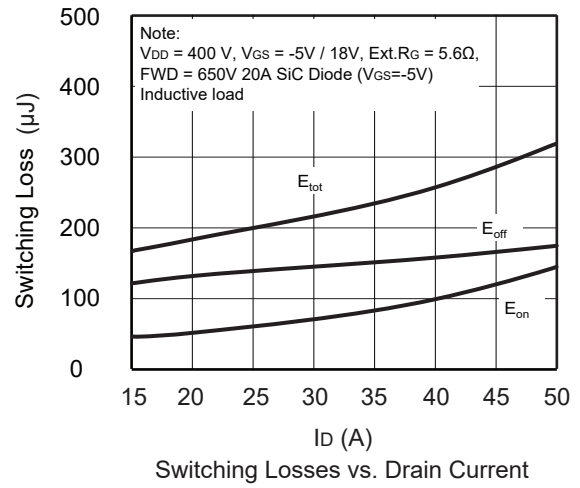
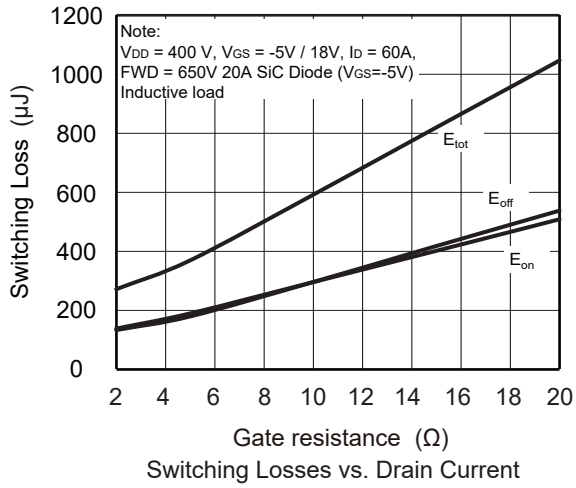


Switching Losses vs. Drain Current



Switching Losses vs. Drain Current

Typical Characteristics



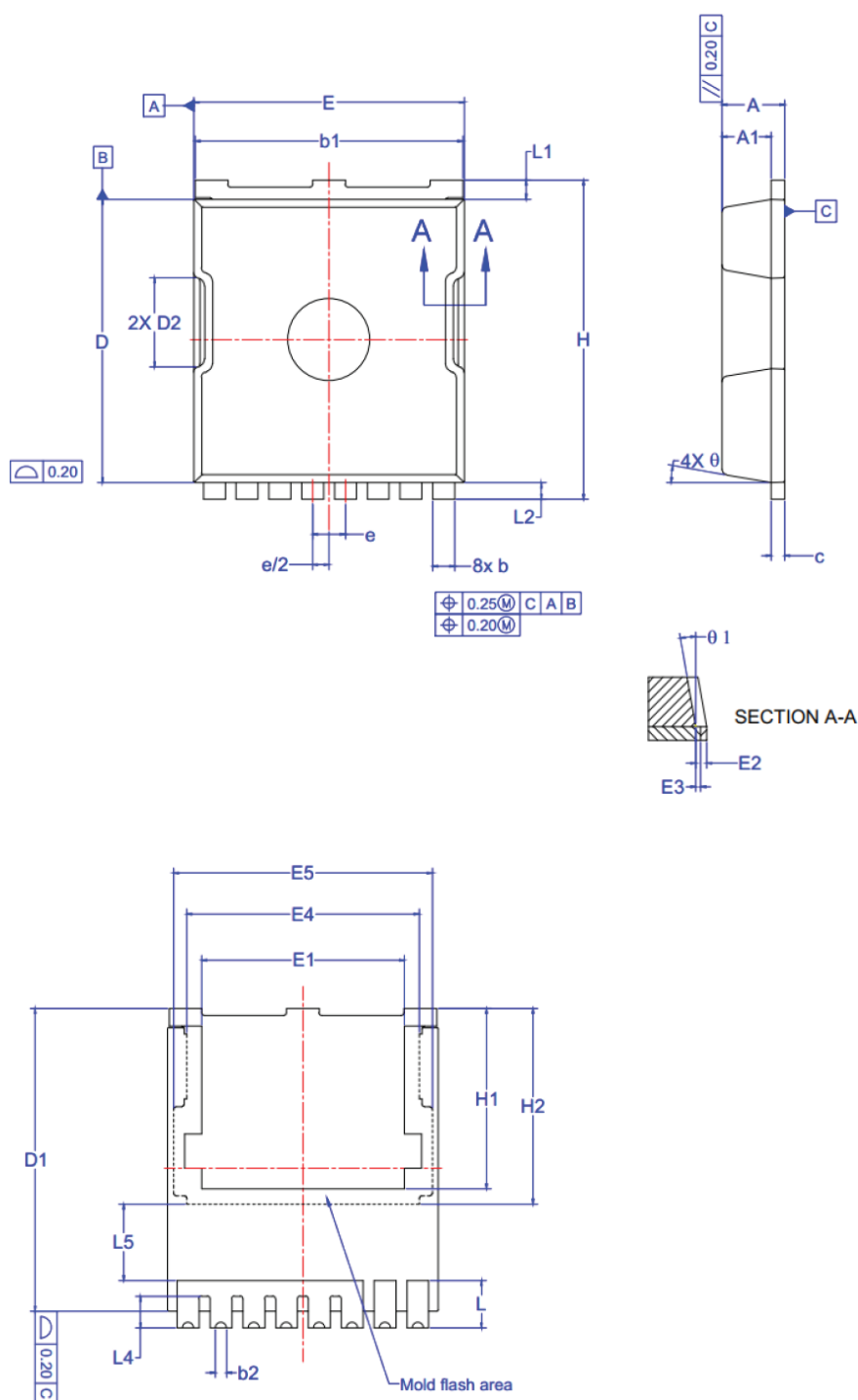
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Package Dimension

TOLL

Unit :mm



SYMBOL	MIN.	NOM.	MAX.
A	2.20	2.30	2.40
A1	1.70	1.80	1.90
b	0.70	0.80	0.90
b1	9.70	9.80	9.90
b2	0.36	0.41	0.51
c	0.40	0.50	0.60
D	10.28	10.38	10.48
D1	10.98	11.08	11.18
D2	3.30		
E	9.80	9.90	10.00
E1	7.32	7.42	7.52
E2	0.30	0.40	0.50
E3	0.15	0.18	0.21
E4	8.50		
E5	9.46		
e	1.20 BASIC		
H	11.58	11.68	11.78
H1	6.55	6.65	6.75
H2	7.05	7.15	7.25
L	1.63	1.73	1.83
L1	0.60	0.70	0.80
L2	0.50	0.60	0.70
L4	1.00	1.15	1.30
L5	2.70	2.80	2.90
N	8		
θ	10° REF.		
θ1	10° REF.		

* Dimensions in millimeters